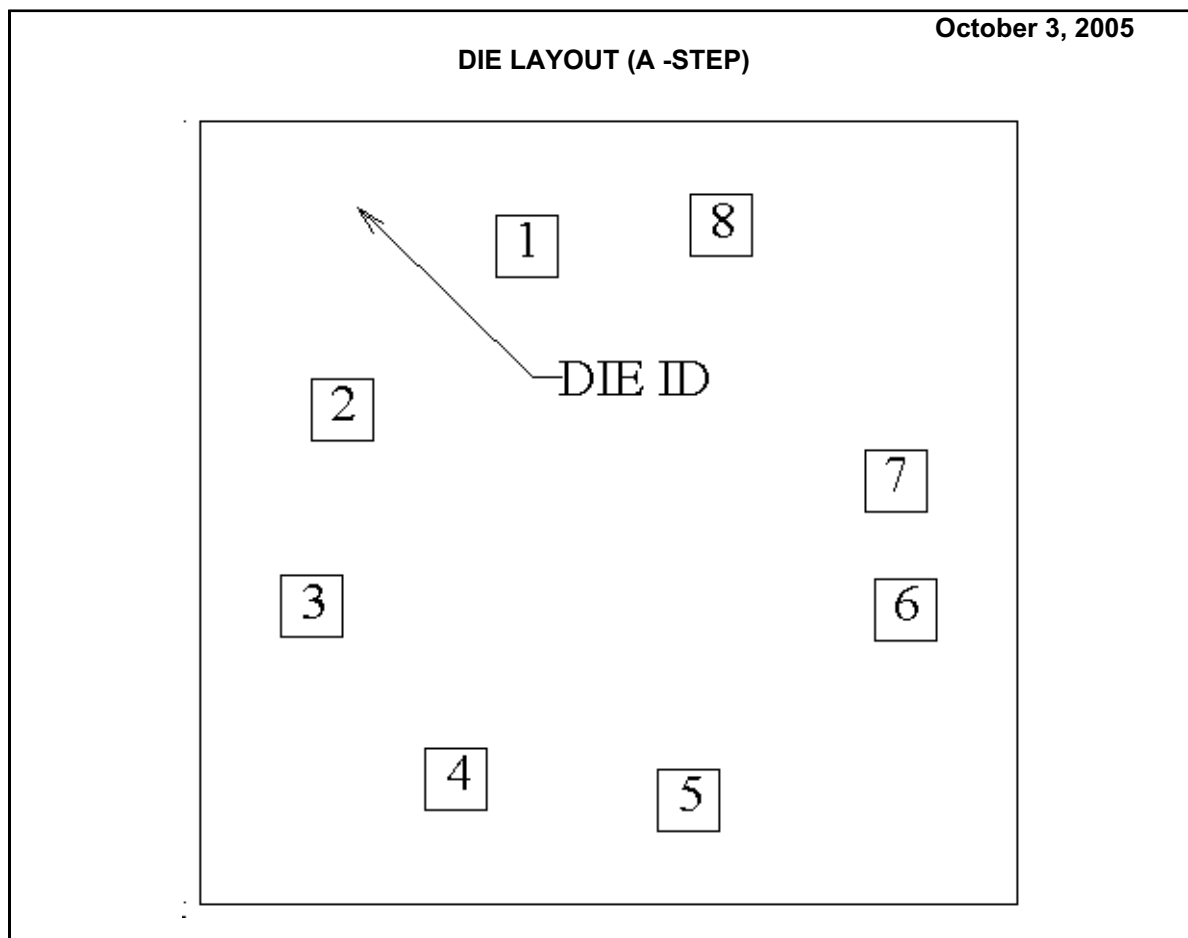


LMC555 MD8 MW8
CMOS TIMER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC555A	Bond Pad Opening Size (min)	88μm x 88μm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1118μm x 1168μm 44.0mils x 46.0mils	Back Side Connection	Floating
Thickness	330μm Nominal		
Min Pitch	185μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
GND	1	-116	382	88	x	88
/TRIGGER	2	-382	148	88	x	88
OUTPUT	3	-424	-134	88	x	88
/RESET	4	-218	-380	88	x	88
CONT VOLTAGE	5	114	-410	88	x	88
THRESHOLD	6	424	-138	88	x	88
DISCHARGE	7	410	46	88	x	88
V+	8	162	410	88	x	88

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